

WHAT IS CLAIMED

1. A probe card configured to be used to inspect integrated circuits formed on a semiconductor-wafer, comprising:

a resin insulating layer and a conductor circuit serially formed in alternate fashion and in repetition on a ceramic board.

2. The probe card according to claim 1,

wherein a conductor-filled through hole is formed in said ceramic board.

3. The probe card according to claim 1,

wherein resultant conductor circuits formed through said resin layer are interconnected each other by a via hole.

4. The probe card according to claim 1, wherein said ceramic board comprises non-oxide ceramic.

5. The probe card according to claim 1, wherein said resin layer comprises thermosetting resin.

6. The probe card according to claim 1, wherein said ceramic board has a disc shape.

7. The probe card according to claim 1, wherein said resin layer is formed so as to cover a whole of at least one main face of said ceramic board.